

N-channel 800 V, 3.5  $\Omega$  typ., 2 A Zener-protected SuperMESH™ 5 Power MOSFET in DPAK, TO-220FP, TO-220 and IPAK packages

Datasheet – production data

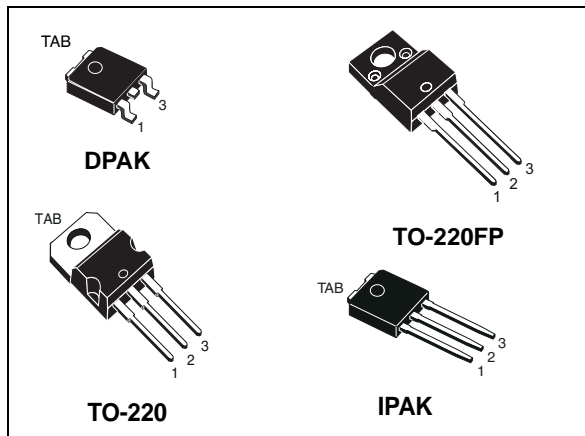
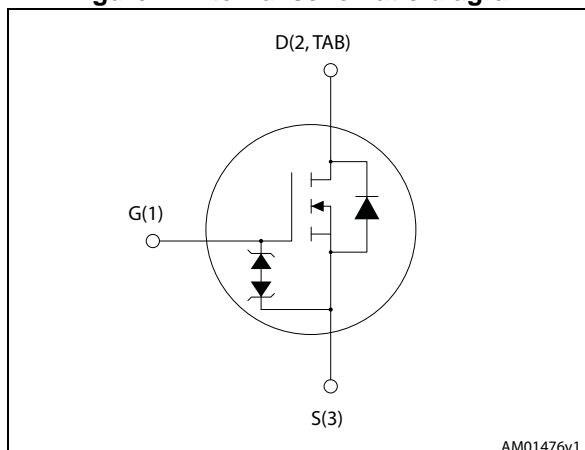


Figure 1. Internal schematic diagram



## Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>	P <sub>TOT</sub>
STD2N80K5	800 V	4.5 $\Omega$	2 A	45 W
STF2N80K5				20 W
STP2N80K5				45 W
STU2N80K5				

- TO-220 worldwide best R<sub>DS(on)</sub>
- Worldwide best FOM (figure of merit)
- Ultra low gate charge
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications

## Description

These devices are N-channel Power MOSFETs developed using SuperMESH™ 5 technology. This revolutionary, avalanche-rugged, high voltage Power MOSFET technology is based on an innovative proprietary vertical structure. The result is a drastic reduction in on-resistance and ultra low gate charge for applications which require superior power density and high efficiency.

Table 1. Device summary

Order codes	Marking	Package	Packaging
STD2N80K5	2N80K5	DPAK	Tape and reel
STF2N80K5		TO-220FP	Tube
STP2N80K5		TO-220	
STU2N80K5		IPAK	

# Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		DPAK, TO-220, IPAK	TO-220FP	
$V_{GS}$	Gate- source voltage	30		V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	2 <sup>(1)</sup>		A
$I_D$	Drain current (continuous) at $T_C = 100\text{ °C}$	1.3		A
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	8		A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ °C}$	45	20	W
$I_{AR}$	Max current during repetitive or single pulse avalanche (pulse width limited by $T_{jmax}$ )	0.5		A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25\text{ °C}$ , $I_D = I_{AS}$ , $V_{DD} = 50\text{ V}$ )	60.5		mJ
$dv/dt$ <sup>(3)</sup>	Peak diode recovery voltage slope	4.5		V/ns
$dv/dt$ <sup>(4)</sup>	MOSFET $dv/dt$ ruggedness	50		V/ns
$T_j$	Operating junction temperature	-55 to 150		°C
$T_{stg}$	Storage temperature			°C

1. For TO-220FP limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 2\text{ A}$ ,  $di/dt \leq 100\text{ A}/\mu\text{s}$ , peak  $V_{DS} \leq V_{(BR)DSS}$
4.  $V_{DS} \leq 640\text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value				Unit
		DPAK	TO-220FP	TO-220	IPAK	
$R_{thj-case}$	Thermal resistance junction-case	2.78	6.25	2.78	2.78	°C/W
$R_{thj-pcb}$	Thermal resistance junction-pcb	50 <sup>(1)</sup>				
$R_{thj-amb}$	Thermal resistance junction-amb		62.5		100	

1. When mounted on FR-4 board of 1 inch<sup>2</sup>, 2 oz Cu.

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified).

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 1\text{ mA}$	800			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 800\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 800\text{ V}$ , $T_J = 125\text{ °C}$			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 100\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 1\text{ A}$		3.5	4.5	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$	-	105	-	pF
$C_{oss}$	Output capacitance		-	8	-	pF
$C_{rss}$	Reverse transfer capacitance		-	0.5	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{GS} = 0$ , $V_{DS} = 0\text{ to }640\text{ V}$	-	16	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	7	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_D = 0$	-	18	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 640\text{ V}$ , $I_D = 2\text{ A}$ $V_{GS} = 10\text{ V}$	-	9.5	-	nC
$Q_{gs}$	Gate-source charge		-	1.5	-	nC
$Q_{gd}$	Gate-drain charge		-	7.5	-	nC

1. Time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$
2. Energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400\text{ V}$ , $I_D = 1\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$	-	8	-	ns
$t_r$	Rise time		-	12	-	ns
$t_{d(off)}$	Turn-off delay time		-	19	-	ns
$t_f$	Fall time		-	32	-	ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		2	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		8	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 2\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 2\text{ A}$ , $V_{DD} = 60\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	255		ns
$Q_{rr}$	Reverse recovery charge		-	1		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	8		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 2\text{ A}$ , $V_{DD} = 60\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 150\text{ }^\circ\text{C}$	-	285		ns
$Q_{rr}$	Reverse recovery charge		-	1.45		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	7.5		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1\text{ mA}$ , $I_D = 0$	30	-	-	V

The built-in back-to-back Zener diodes have been specifically designed to enhance not only the device’s ESD capability, but also to make them capable of safely absorbing any voltage transients that may occasionally be applied from gate to source. In this respect, the Zener voltage is appropriate to achieve efficient and cost-effective protection of device integrity. The integrated Zener diodes thus eliminate the need for external components.

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for DPAK and IPAK

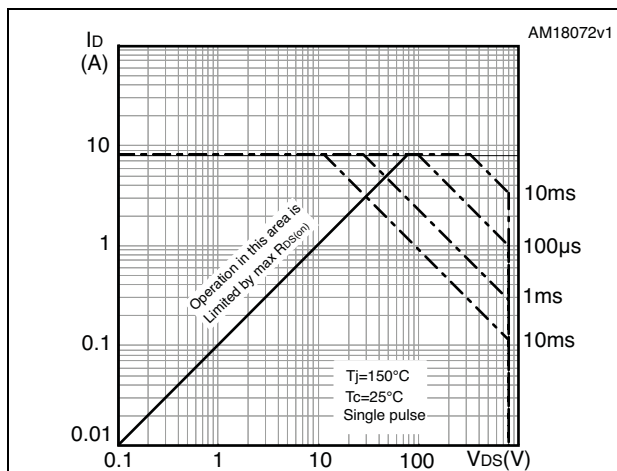


Figure 3. Thermal impedance for DPAK and IPAK

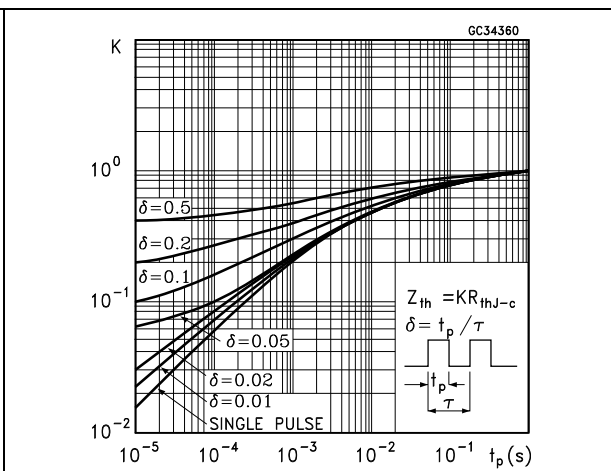


Figure 4. Safe operating area for TO-220FP

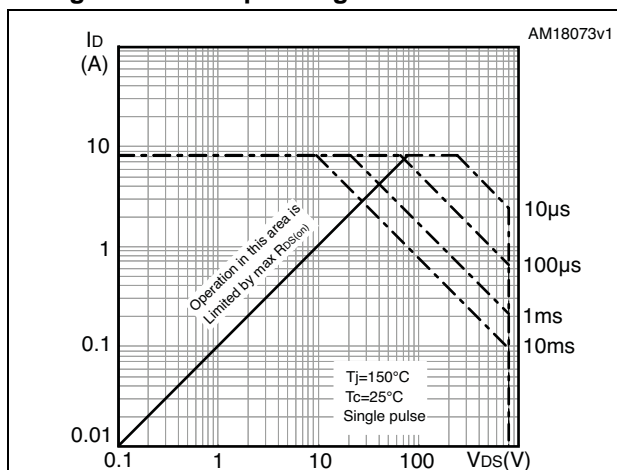


Figure 5. Thermal impedance for TO-220FP

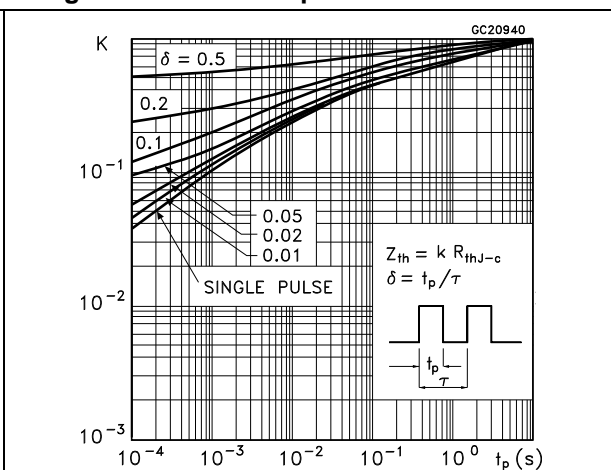


Figure 6. Safe operating area for TO-220

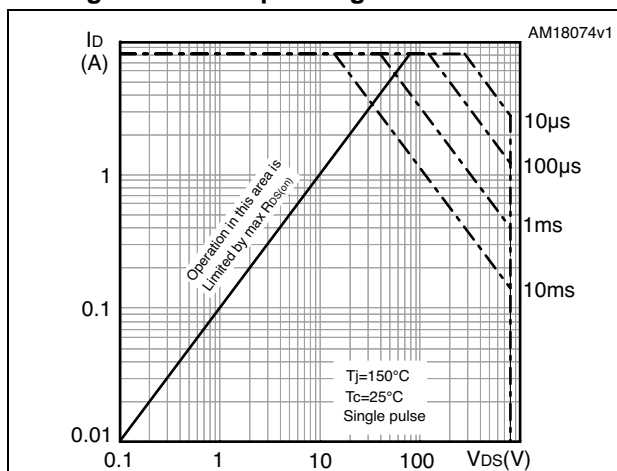


Figure 7. Thermal impedance for TO-220

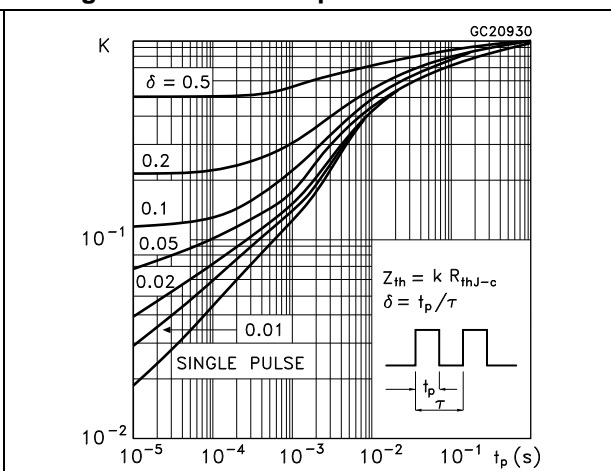


Figure 8. Output characteristics

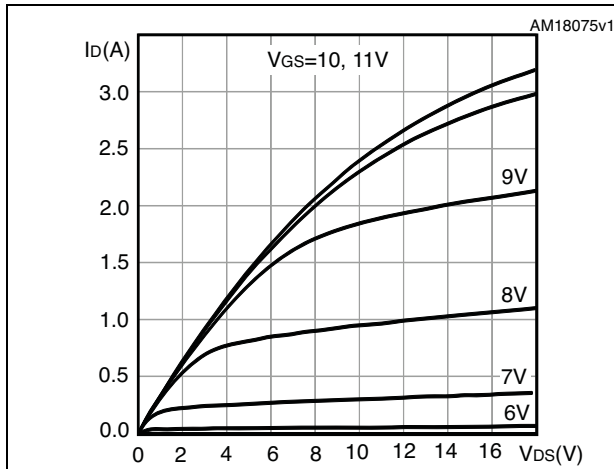


Figure 9. Transfer characteristics

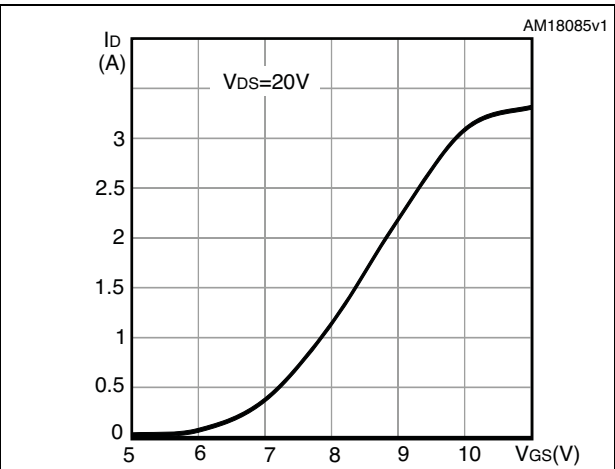


Figure 10. Gate charge vs gate-source voltage

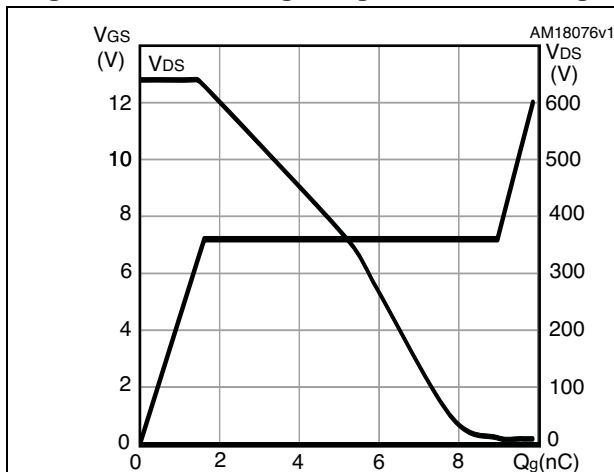


Figure 11. Static drain-source on-resistance

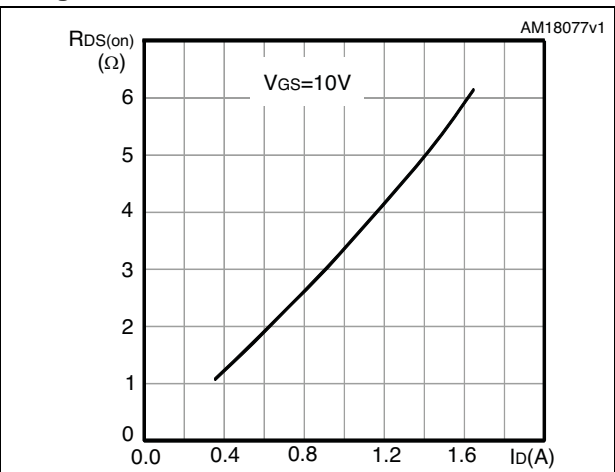


Figure 12. Capacitance variations

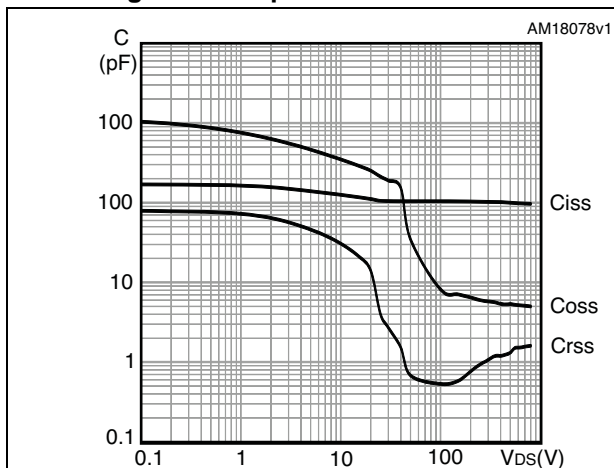


Figure 13. Output capacitance stored energy

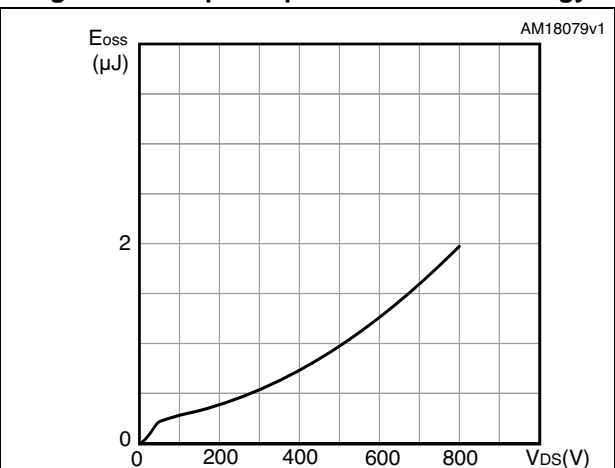


Figure 14. Normalized gate threshold voltage vs temperature

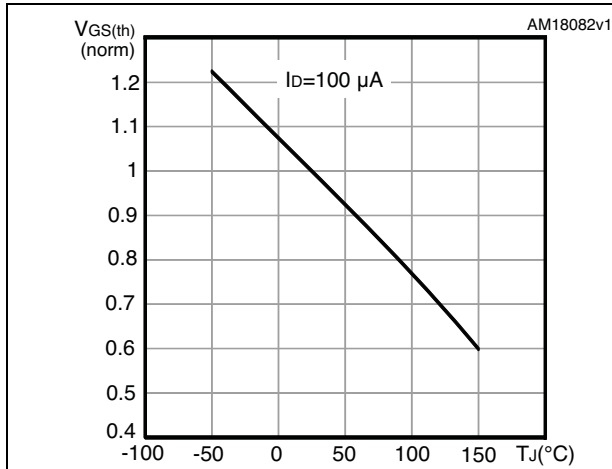


Figure 15. Normalized on-resistance vs temperature

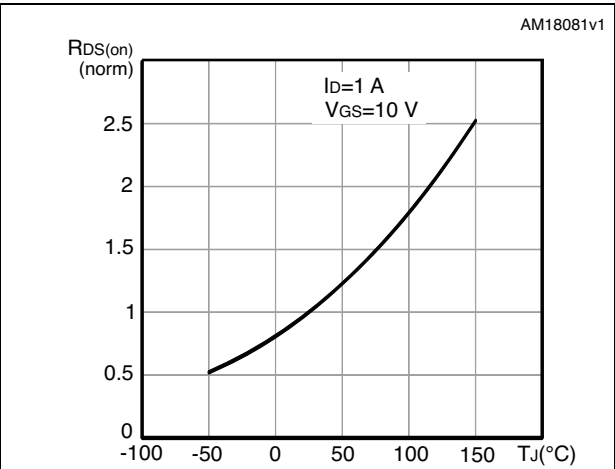


Figure 16. Normalized V<sub>DS</sub> vs temperature

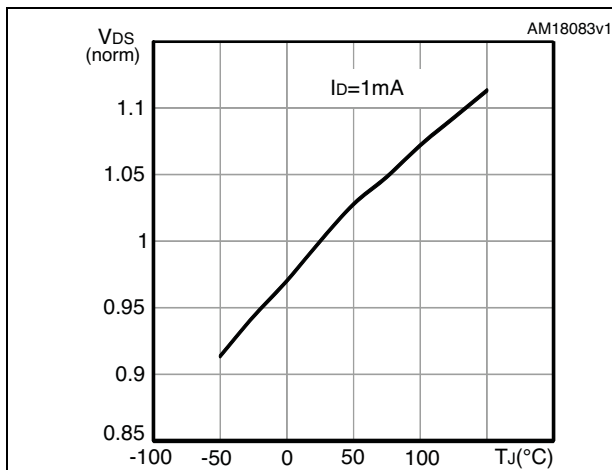


Figure 17. Source-drain diode forward characteristics

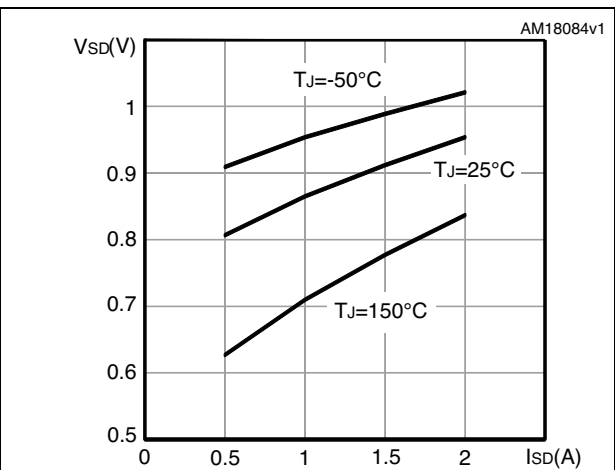
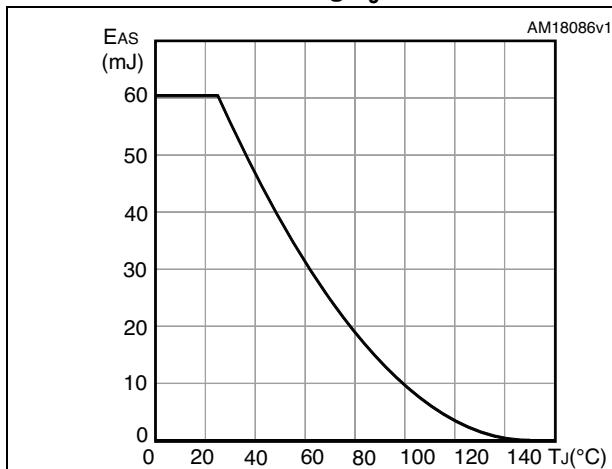


Figure 18. Maximum avalanche energy vs starting T<sub>J</sub>





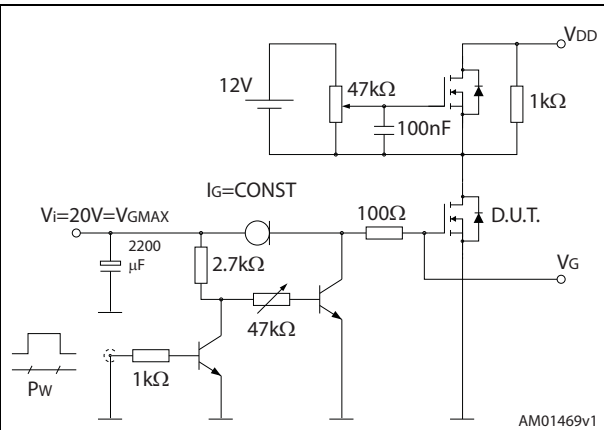
### 3 Test circuits

Figure 19. Switching times test circuit for resistive load



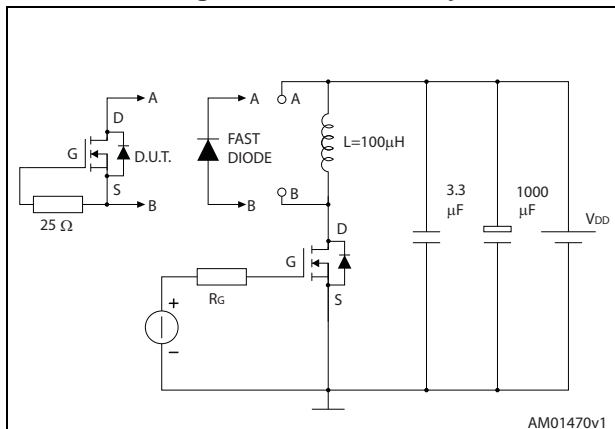
AM01468v1

Figure 20. Gate charge test circuit



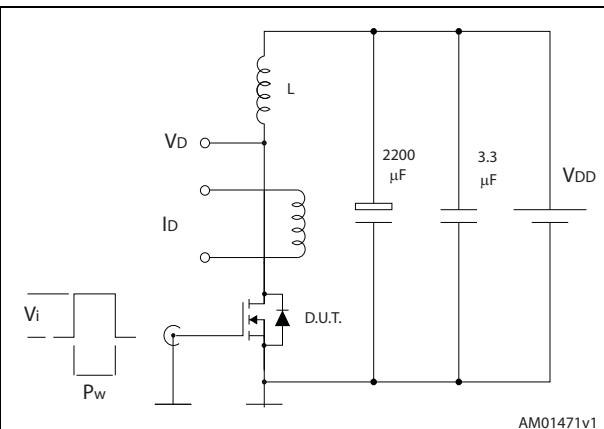
AM01469v1

Figure 21. Test circuit for inductive load switching and diode recovery times



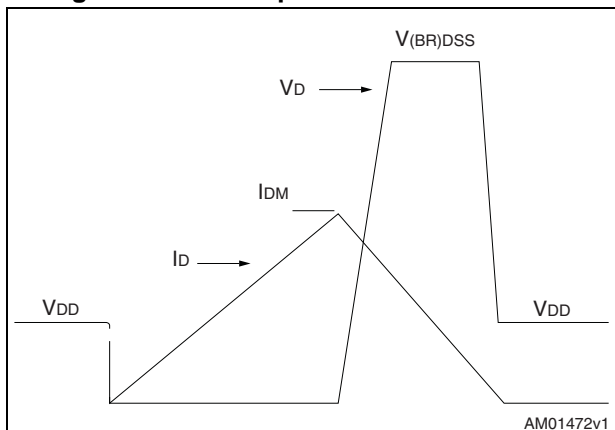
AM01470v1

Figure 22. Unclamped inductive load test circuit



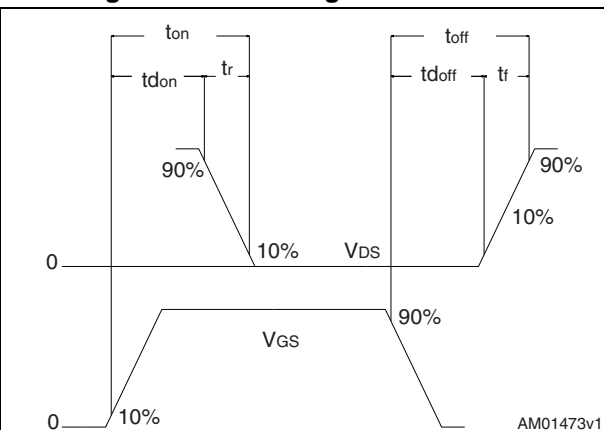
AM01471v1

Figure 23. Unclamped inductive waveform



AM01472v1

Figure 24. Switching time waveform



AM01473v1

## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

Figure 25. DPAK (TO-252) type A drawing

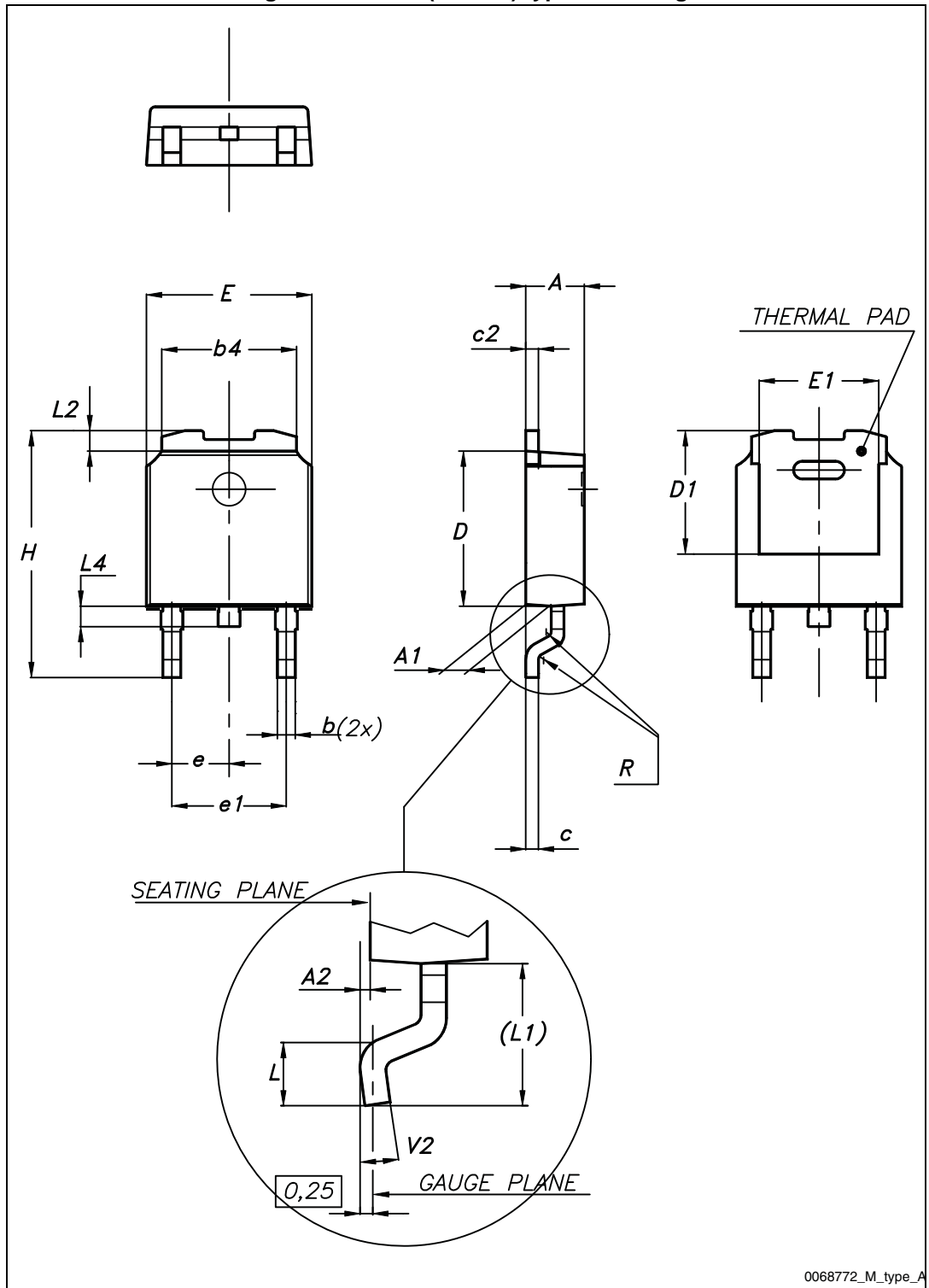
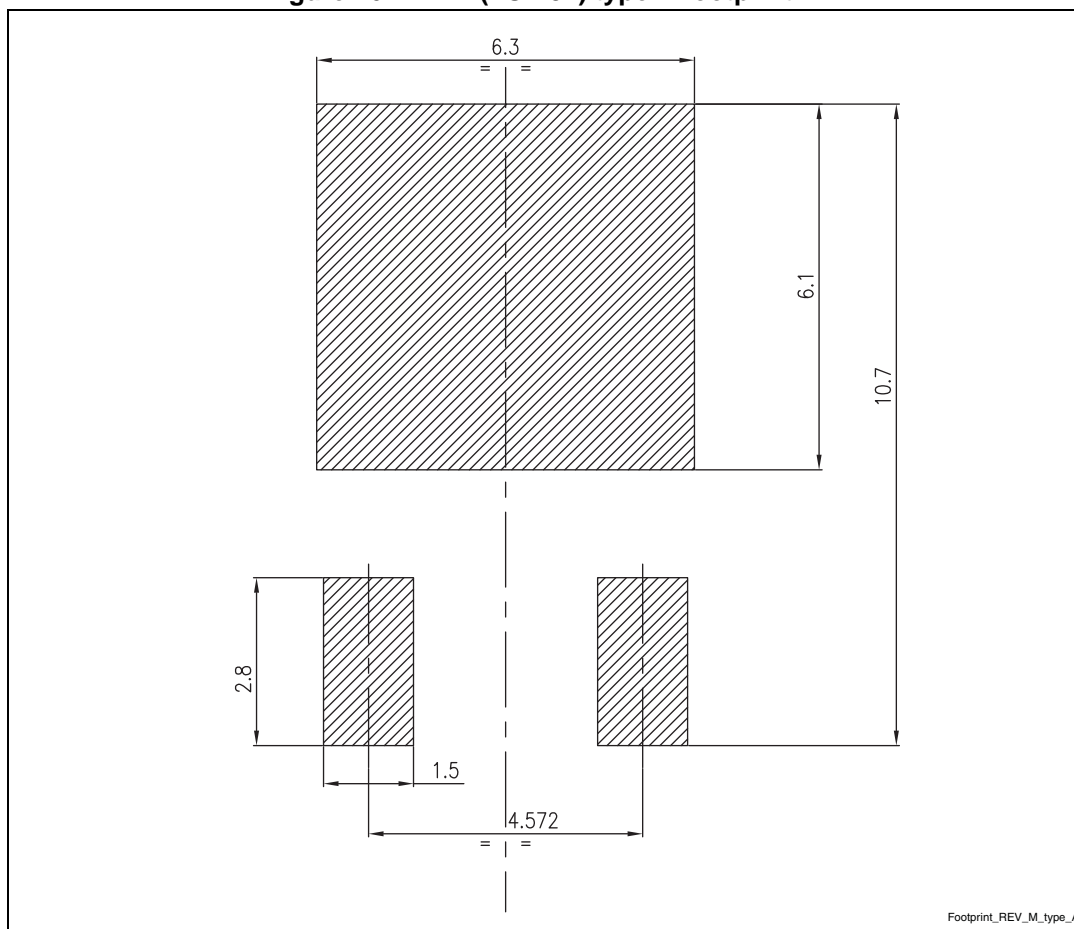


Table 9. DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)		2.80	
L2		0.80	
L4	0.60		1.00
R		0.20	
V2	0°		8°

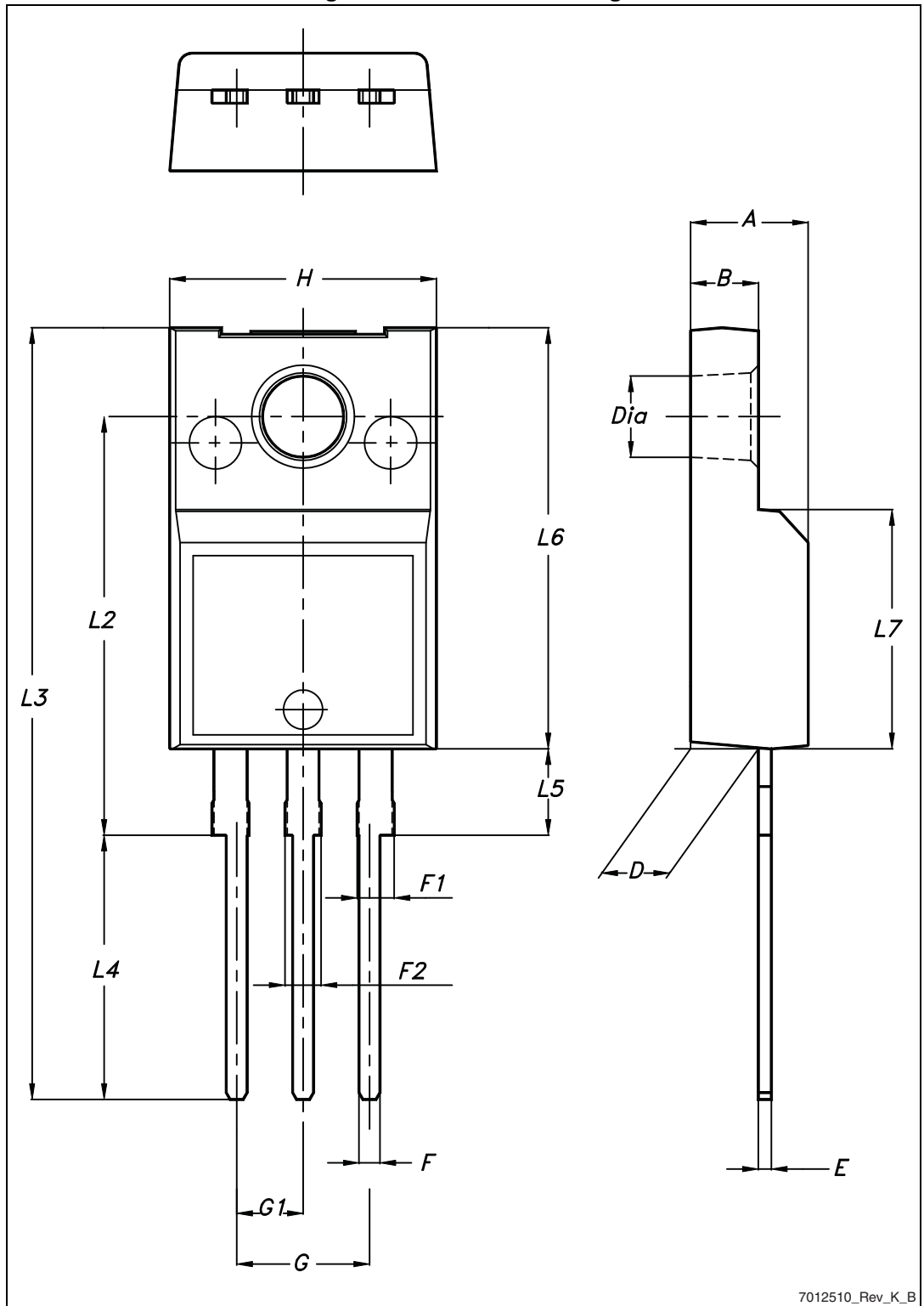
Figure 26. DPAK (TO-252) type A footprint (a)



Footprint\_REV\_M\_type\_A

a. All dimensions are in millimeters

Figure 27. TO-220FP drawing

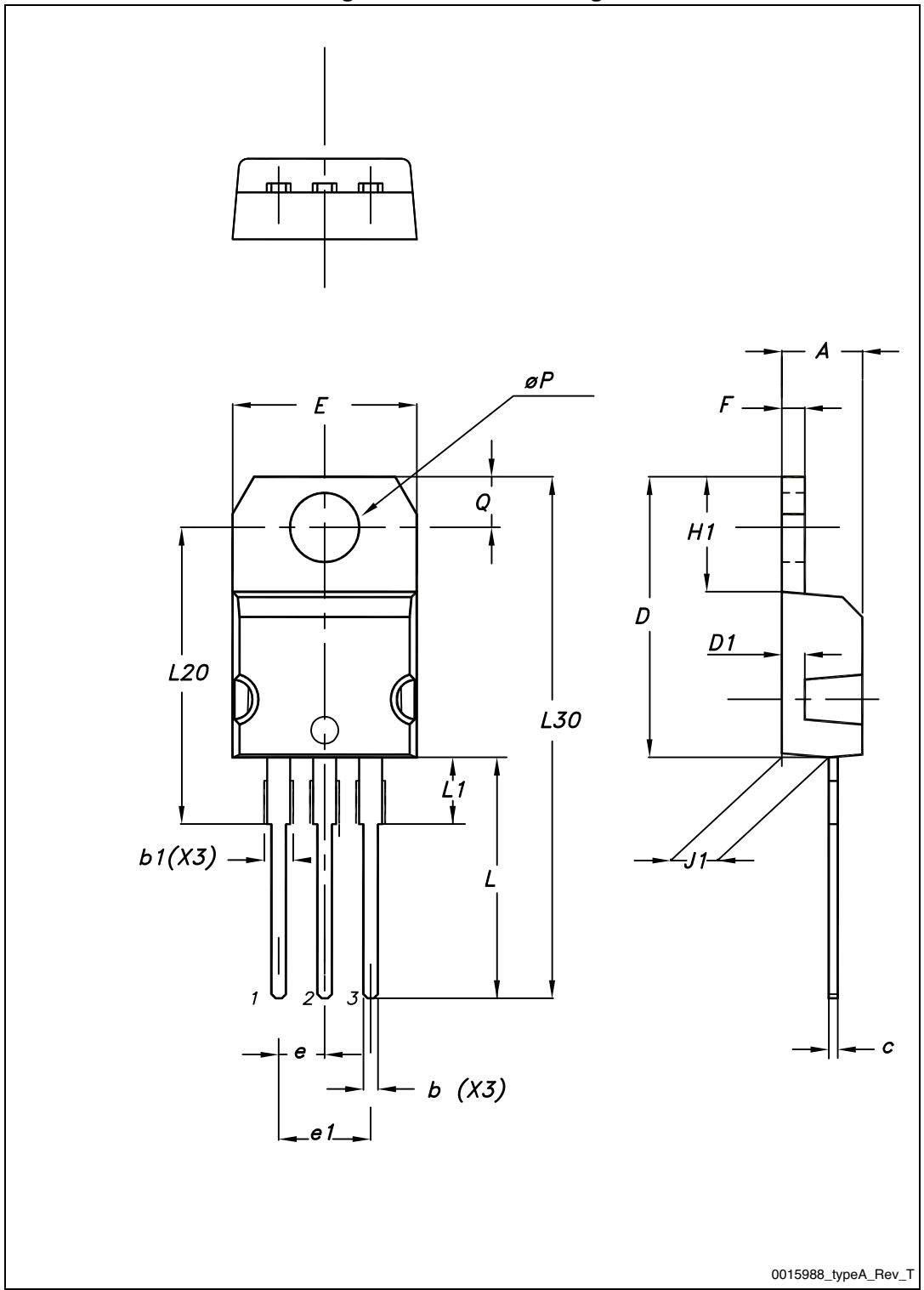


7012510\_Rev\_K\_B

Table 10. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 28. TO-220 drawing



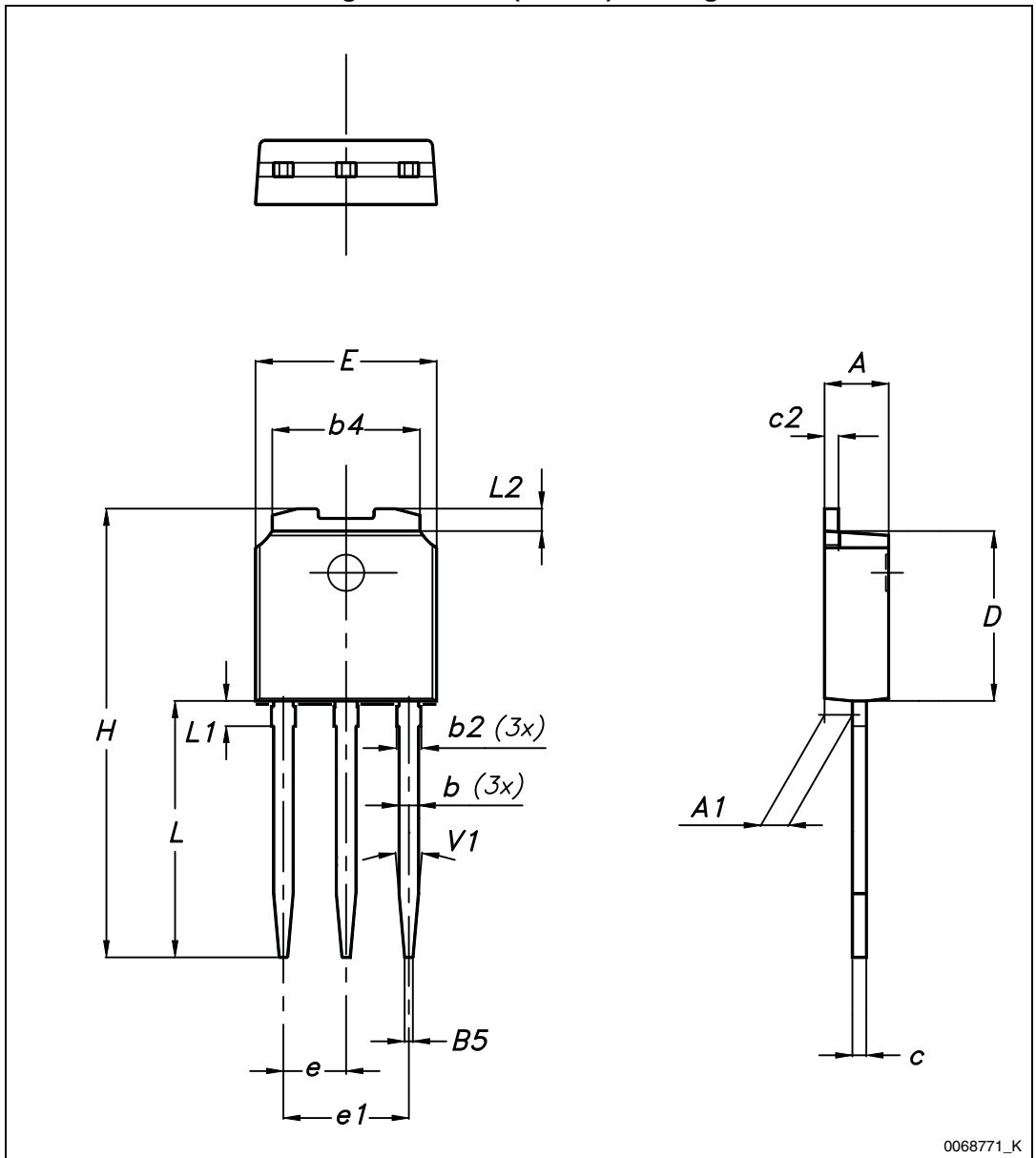
0015988\_typeA\_Rev\_T



Table 11. TO-220 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 29. IPAK (TO-251) drawing



0068771\_K

Table 12. IPAK (TO-251) mechanical data

DIM	mm.		
	min.	typ.	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

# 5 Packaging information

Figure 30. Tape for DPAK

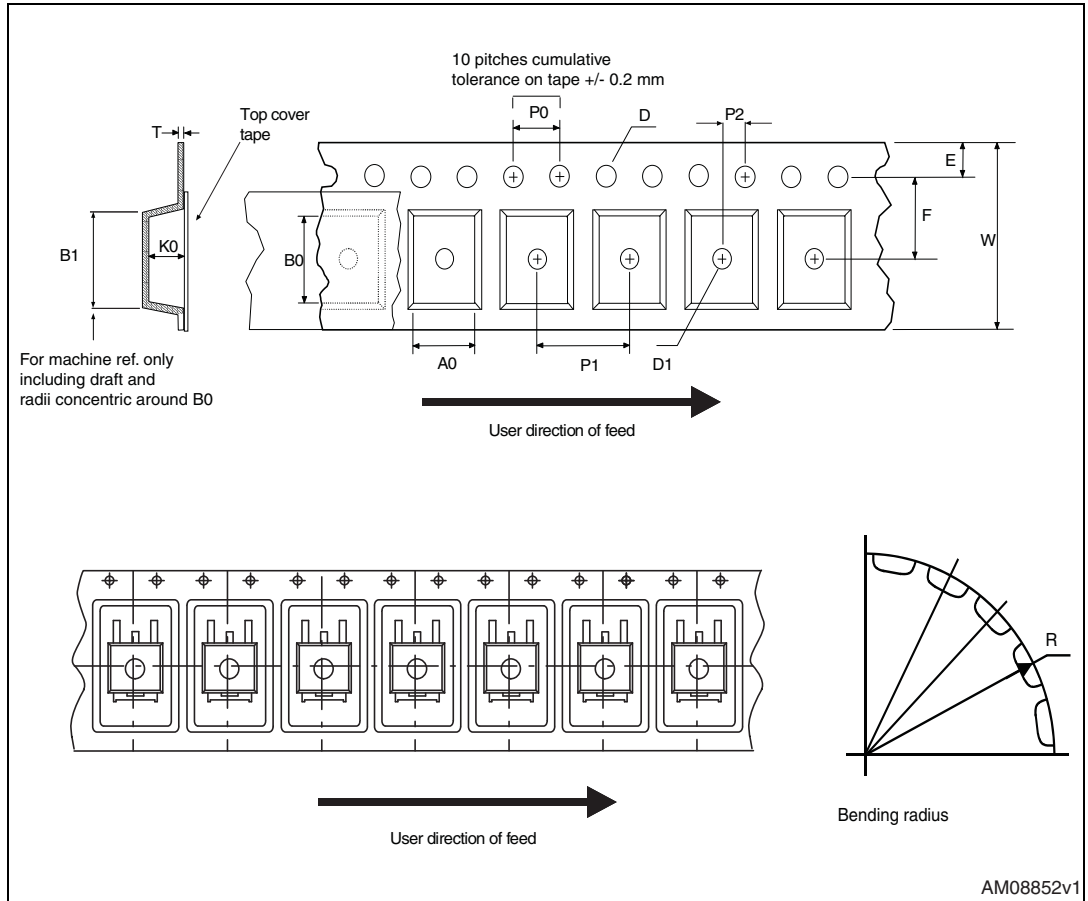


Figure 31. Reel for DPAK

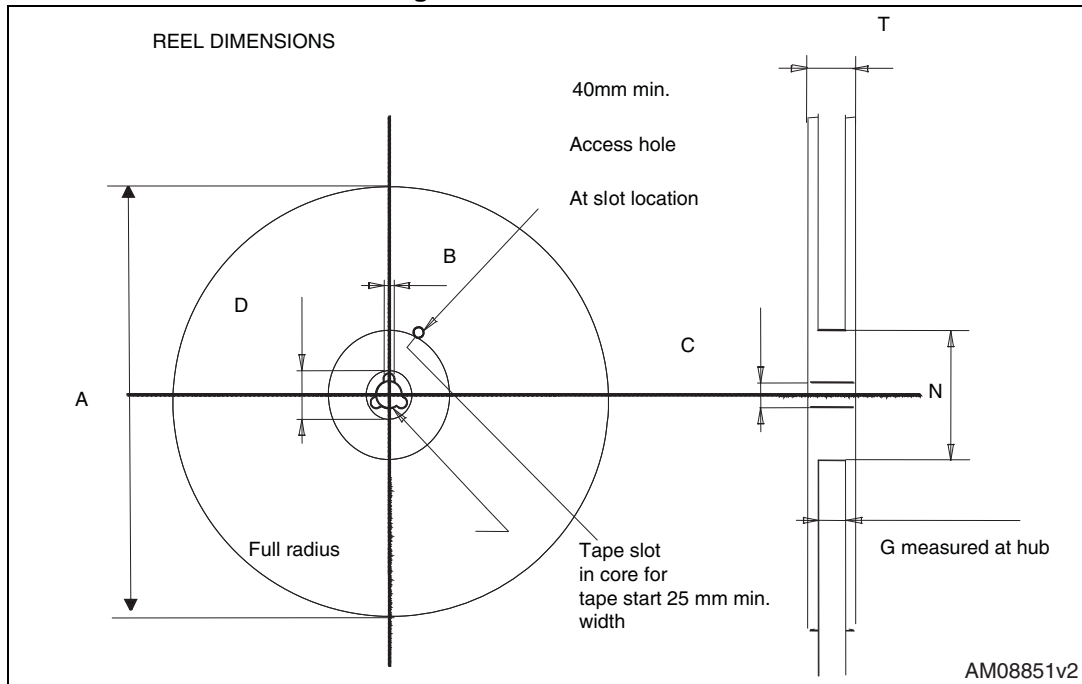


Table 13. DPAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## 6 Revision history

Table 14. Document revision history

Date	Revision	Changes
11-Jul-2013	1	First release.
18-Feb-2014	2	<ul style="list-style-type: none"><li>– Added: IPAK package</li><li>– Modified: <math>E_{AS}</math> value in <a href="#">Table 2</a></li><li>– Modified: <math>R_{thj-case}</math> in <a href="#">Table 3</a></li><li>– Modified: typical values in <a href="#">Table 5</a>, <a href="#">6</a> and <a href="#">7</a></li><li>– Added: <a href="#">Section 2.1: Electrical characteristics (curves)</a></li><li>– Updated: <a href="#">Figure 25</a>, <a href="#">26</a> and <a href="#">Table 9</a></li><li>– Added: <a href="#">Table 12</a> and <a href="#">Figure 29</a></li><li>– Minor text changes</li></ul>

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